

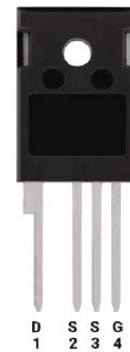


Description

Silicon Carbide (SiC) MOSFET use a completely new technology that provide superior switching performance and higher reliability compared to Silicon. In addition, the low ON resistance and compact chip size ensure low capacitance and gate charge. Consequently, system benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size.

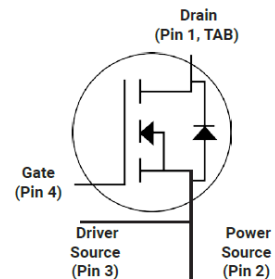
Features

- High Speed Switching with Low Capacitances
- High Blocking Voltage with Low RDS(on)
- Simple to drive with Standard Gate Drive
- 100% avalanche tested
- Maximum junction temperature of 150°C
- ROHS Compliant



Application

- EV Charging
- DC-AC Inverters
- High Voltage DC/DC Converters
- Switch Mode Power Supplies
- Power Factor Correction Modules
- Motor Drives



Ordering Information

Part Number	Marking	Package	Packaging
ASC60N1200MT4	ASC60N1200MT4	TO-247	Tube



ASC60N1200MT4

Absolute Maximum Ratings($T_c=25^\circ\text{C}$)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage	1200	V
I_D	Drain Current(continuous)at $T_c=25^\circ\text{C}$	60	A
I_D	Drain Current(continuous)at $T_c=100^\circ\text{C}$	40	A
I_{DM}	Drain Current (pulsed)	160	A
V_{GS}	Gate-Source Voltage	-10/+22	V
P_D	Power Dissipation $T_c = 25^\circ\text{C}$	328	W
T_J, T_{stg}	Junction and Storage Temperature Range	-55 to +150	$^\circ\text{C}$

Electrical Characteristics($T_J = 25^\circ\text{C}$ unless otherwise specified)

Typical Performance-Static

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
BV_{DS}	Drain-source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	1200			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=1200\text{V}, V_{GS}=0\text{V}, T_J=25^\circ\text{C}$			100	μA
I_{GSS}	Gate-body Leakage Current	$V_{GS}=20\text{V}, V_{DS}=0\text{V}$			250	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=10\text{mA}$	2		4	V
$R_{DS(on)}$	Static Drain-source On Resistance	$V_{GS}=20\text{V}, I_D=40\text{A}$		33	45	$\text{m}\Omega$
R_G	Gate Resistance	$V_{GS}=0\text{V}, f=1\text{MHz}$		5		Ω

Typical Performance-Dynamic

C_{iss}	Input Capacitance	$V_{DS}=800\text{V}, f=1\text{MHz}, V_{GS}=0\text{V}$		1950		pF
C_{oss}	Output Capacitance			185		pF
C_{riss}	Reverse Transfer Capacitance			28		pF
Q_g	Total Gate Charge	$V_{DS}=800\text{V}, I_D=40\text{A}, V_{GS}=0\sim 20\text{V}$		126		nC
Q_{gs}	Gate-source Charge			20		nC
Q_{gd}	Gate-Drain Charge			38		nC
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=800\text{V}, I_D=40\text{A}, V_{GS}=-5\text{V}\sim 20\text{V}, R_G=0\Omega, R_L=40\Omega, T_J=25^\circ\text{C}$		22		ns
t_r	Rise Time			56		ns
$t_{d(off)}$	Turn-off Delay Time			32		ns
t_f	Fall Time			35		ns

Typical Performance-Reverse Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{FSD}	Forward Voltage	V _{GS} =0V, I _F =30A, T _J =25°C	3		6	V
		V _{GS} =0V, I _F =30A, T _J =150°C	3		6	V
t _{rr}	Reverse Recovery Time	V _{GS} =0 V, I _F =30 A, V _R =800 V, di/dt= 2000 A/us		58		ns
Q _{rr}	Reverse Recovery Charge			287		nC
I _{rrm}	Peak Reverse Recovery Current			18		A

Thermal Characteristics

Symbol	Parameter	Value.	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case	0.38	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Case	40	°C/W

The values are based on the junction-to case thermal impedance which is measured with the device mounted to a large heat sink assuming maximum junction temperature of T_J(max)=150°C

Electrical Characteristics (25°C unless noted)

Figure 1: Output characteristics ($T_J = 25^\circ\text{C}$)

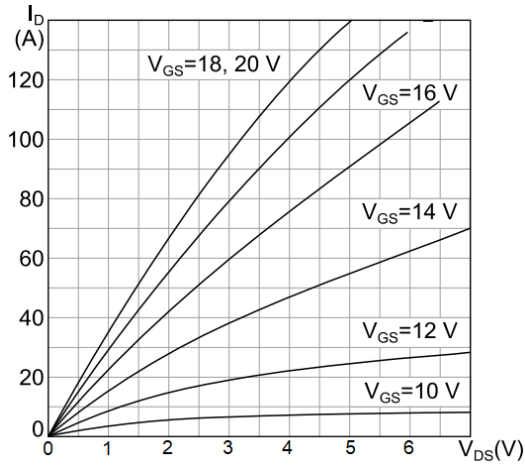


Figure 2: Output characteristics ($T_J = 150^\circ\text{C}$)

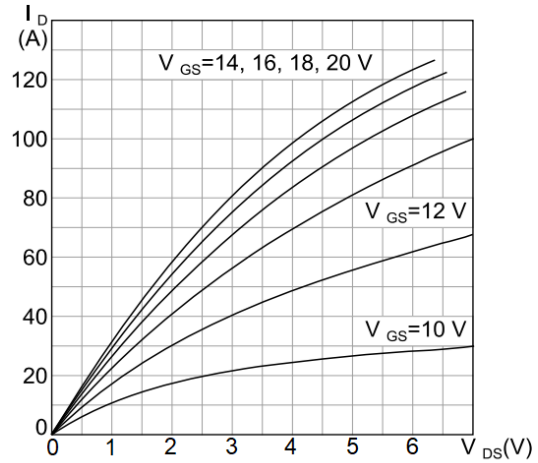


Figure 3: Transfer characteristics

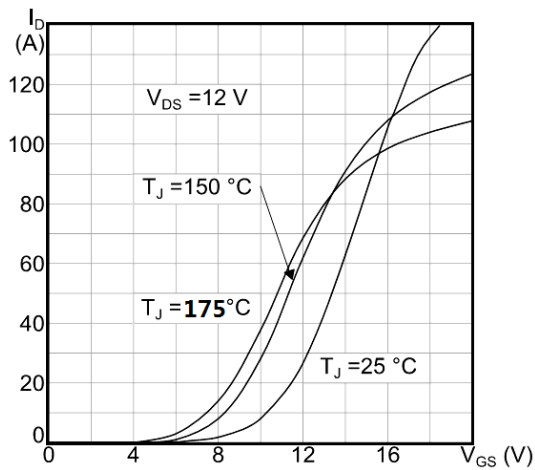


Figure 5: Power dissipation

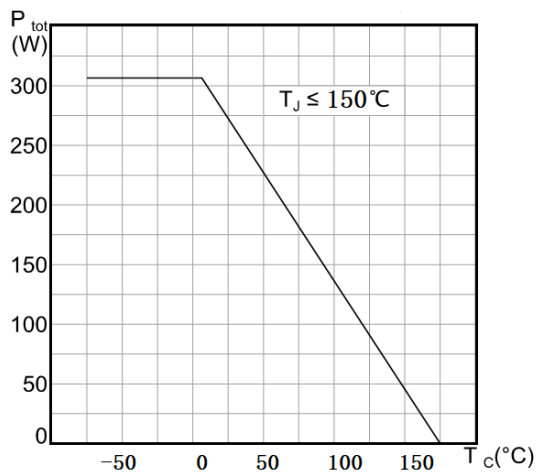


Figure 4 Normalized BVDSS vs. Temperature

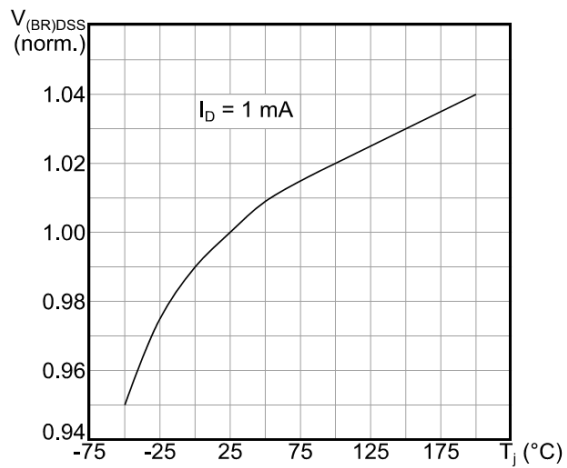


Figure 6: Gate charge vs gate-source voltage

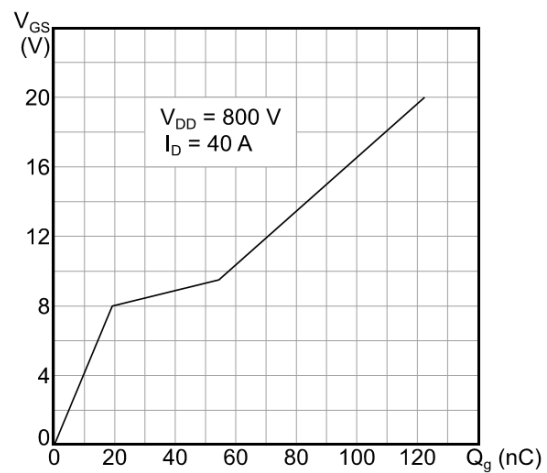


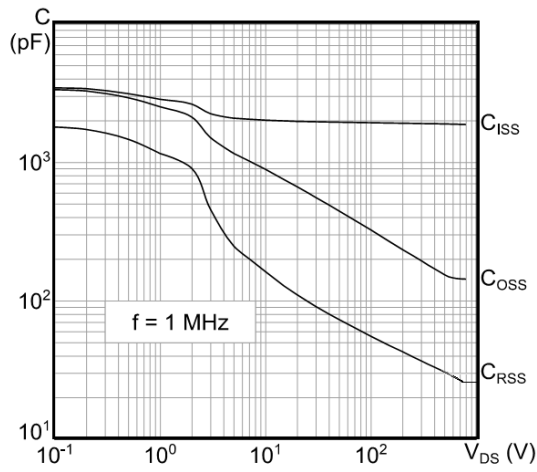
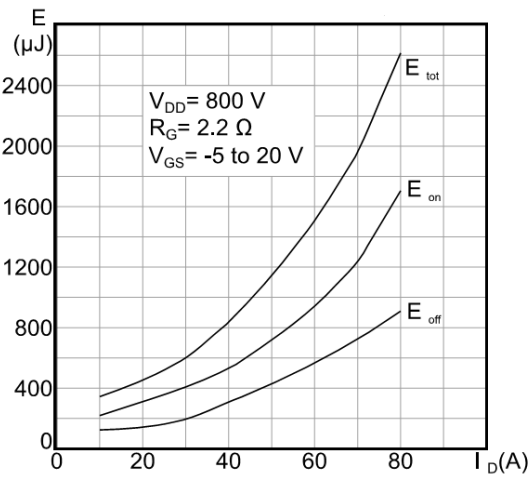
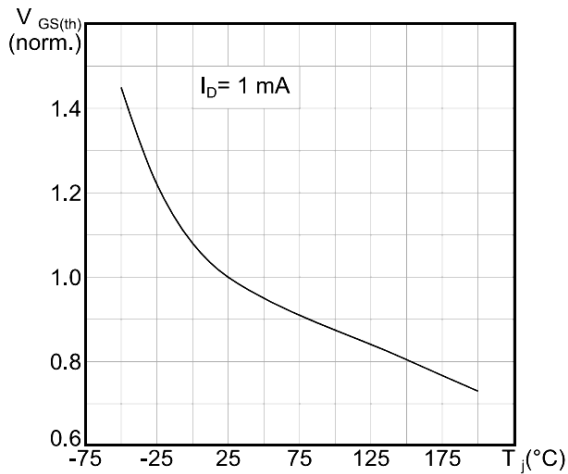
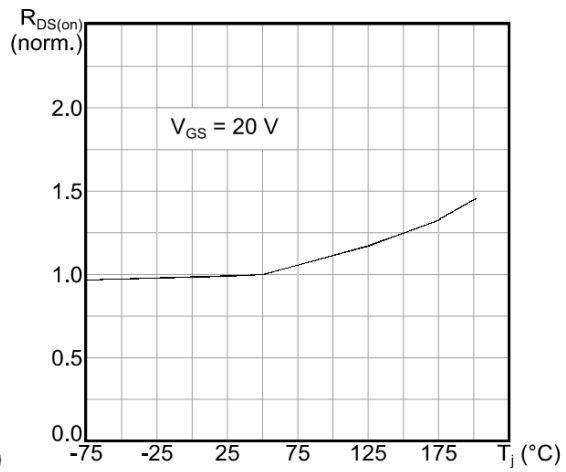
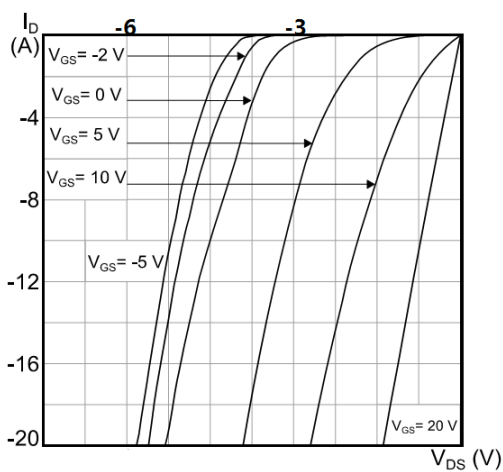
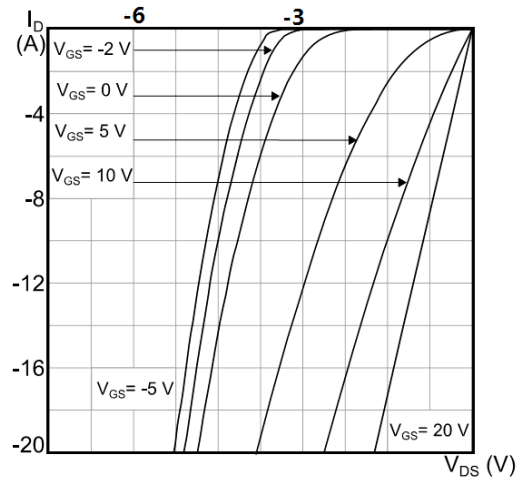
Figure 7: Capacitance variations

Figure 8: Switching energy vs. drain current

Figure 9: Normalized V_{th} vs. T_J

Figure 10: Normalized R_{DS(on)} vs. T_J

Figure 11: Body diode characteristics (T_J = 25 °C)

Figure 12: Body diode characteristics (T_J = 150 °C)


Figure 13: Safe operating area

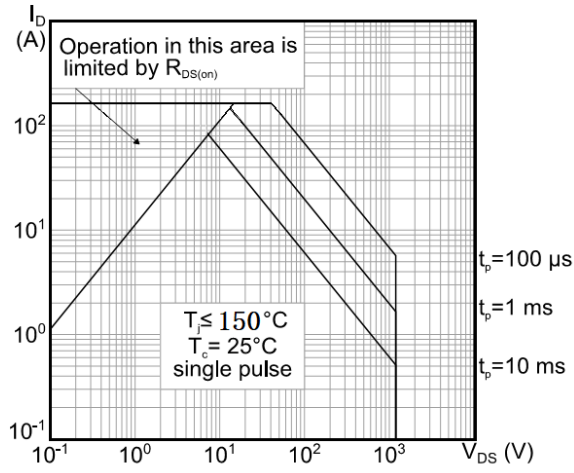


Figure 14: Continuous Ids VS Tc

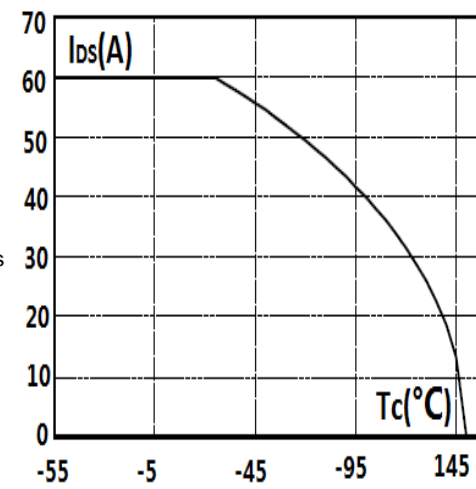
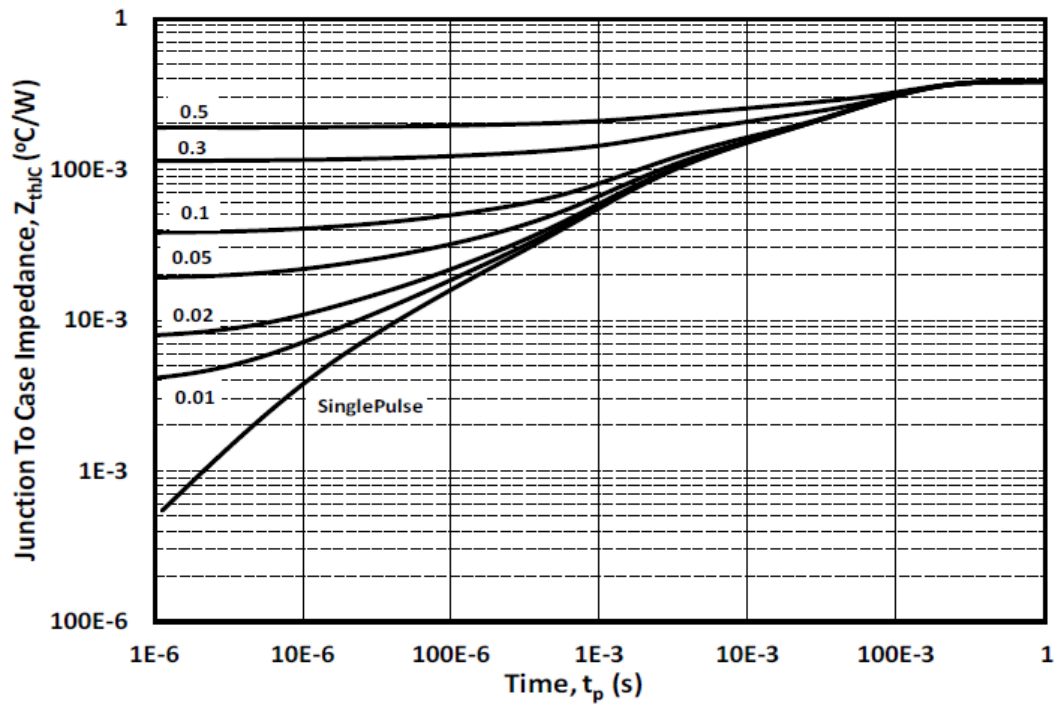
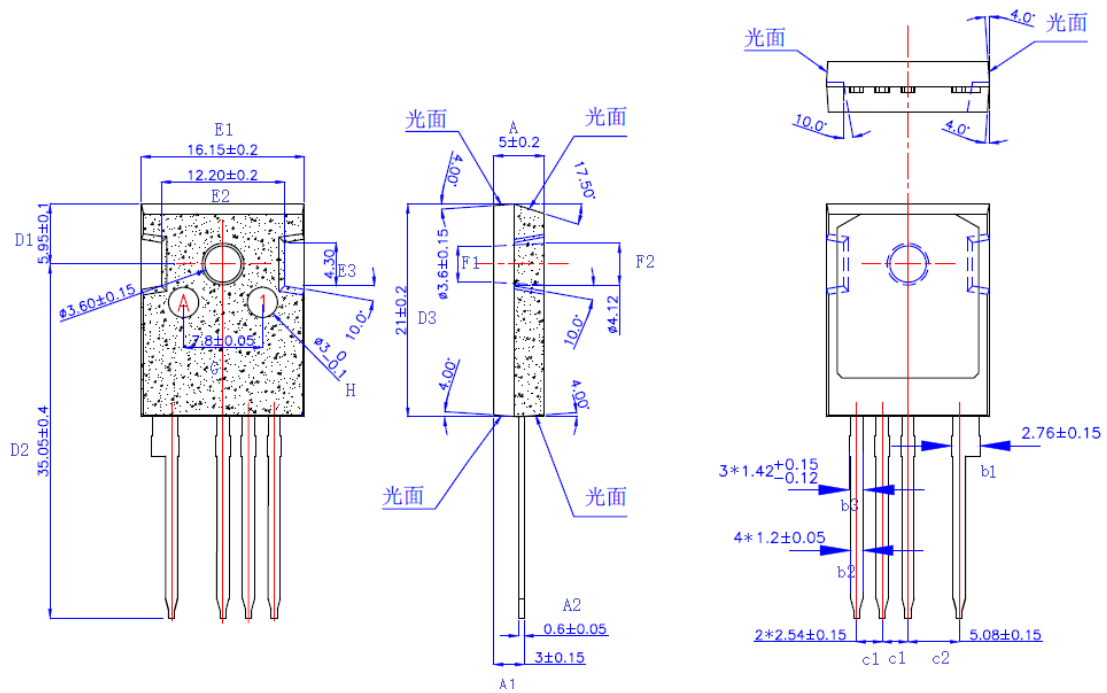


Figure 15: Thermal impedance



Package Drawing:

Dimensions (UNIT: mm)

SYM	MILLIMETERS		SYM	MILLIMETERS	
	MIN	MAX		MIN	MAX
A	4.98	5.02	D2	34.65	35.45
A1	2.85	3.15	D3	20.80	21.20
A2	0.55	0.65	E1	15.95	16.35
b1	2.61	2.91	E2	12.00	12.40
b2	1.15	1.25	F1	3.45	3.75
b3	1.30	1.57	F2	4.12	4.12
c1	2.39	2.69	G	7.75	7.85
c2	4.93	5.23	H	2.90	3.10
D1	5.85	6.05			